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### Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

### Applications of Embedded - CPLDs

#### Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	5 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	2
Number of Macrocells	32
Number of Gates	600
Number of I/O	36
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	<a href="https://www.e-xfl.com/pro/item?MUrl=&amp;PartUrl=epm7032stc44-5">https://www.e-xfl.com/pro/item?MUrl=&amp;PartUrl=epm7032stc44-5</a>

The MAX 7000 architecture supports 100% TTL emulation and high-density integration of SSI, MSI, and LSI logic functions. The MAX 7000 architecture easily integrates multiple devices ranging from PALs, GALs, and 22V10s to MACH and pLSI devices. MAX 7000 devices are available in a wide range of packages, including PLCC, PGA, PQFP, RQFP, and TQFP packages. See [Table 5](#).

**Table 5. MAX 7000 Maximum User I/O Pins** *Note (1)*

Device	44-Pin PLCC	44-Pin PQFP	44-Pin TQFP	68-Pin PLCC	84-Pin PLCC	100-Pin PQFP	100-Pin TQFP	160-Pin PQFP	160-Pin PGA	192-Pin PGA	208-Pin PQFP	208-Pin RQFP
EPM7032	36	36	36									
EPM7032S	36		36									
EPM7064	36		36	52	68	68						
EPM7064S	36		36		68		68					
EPM7096				52	64	76						
EPM7128E					68	84		100				
EPM7128S					68	84	84 (2)	100				
EPM7160E					64	84		104				
EPM7160S					64		84 (2)	104				
EPM7192E								124	124			
EPM7192S								124				
EPM7256E								132 (2)		164		164
EPM7256S											164 (2)	164

**Notes:**

- (1) When the JTAG interface in MAX 7000S devices is used for either boundary-scan testing or for ISP, four I/O pins become JTAG pins.
- (2) Perform a complete thermal analysis before committing a design to this device package. For more information, see the [Operating Requirements for Altera Devices Data Sheet](#).

MAX 7000 devices use CMOS EEPROM cells to implement logic functions. The user-configurable MAX 7000 architecture accommodates a variety of independent combinatorial and sequential logic functions. The devices can be reprogrammed for quick and efficient iterations during design development and debug cycles, and can be programmed and erased up to 100 times.

MAX 7000 devices contain from 32 to 256 macrocells that are combined into groups of 16 macrocells, called logic array blocks (LABs). Each macrocell has a programmable-AND/fixed-OR array and a configurable register with independently programmable clock, clock enable, clear, and preset functions. To build complex logic functions, each macrocell can be supplemented with both shareable expander product terms and high-speed parallel expander product terms to provide up to 32 product terms per macrocell.

The MAX 7000 family provides programmable speed/power optimization. Speed-critical portions of a design can run at high speed/full power, while the remaining portions run at reduced speed/low power. This speed/power optimization feature enables the designer to configure one or more macrocells to operate at 50% or lower power while adding only a nominal timing delay. MAX 7000E and MAX 7000S devices also provide an option that reduces the slew rate of the output buffers, minimizing noise transients when non-speed-critical signals are switching. The output drivers of all MAX 7000 devices (except 44-pin devices) can be set for either 3.3-V or 5.0-V operation, allowing MAX 7000 devices to be used in mixed-voltage systems.

The MAX 7000 family is supported by Altera development systems, which are integrated packages that offer schematic, text—including VHDL, Verilog HDL, and the Altera Hardware Description Language (AHDL)—and waveform design entry, compilation and logic synthesis, simulation and timing analysis, and device programming. The software provides EDIF 2.0.0 and 3.0.0, LPM, VHDL, Verilog HDL, and other interfaces for additional design entry and simulation support from other industry-standard PC- and UNIX-workstation-based EDA tools. The software runs on Windows-based PCs, as well as Sun SPARCstation, and HP 9000 Series 700/800 workstations.



For more information on development tools, see the [MAX+PLUS II Programmable Logic Development System & Software Data Sheet](#) and the [Quartus Programmable Logic Development System & Software Data Sheet](#).

## Functional Description

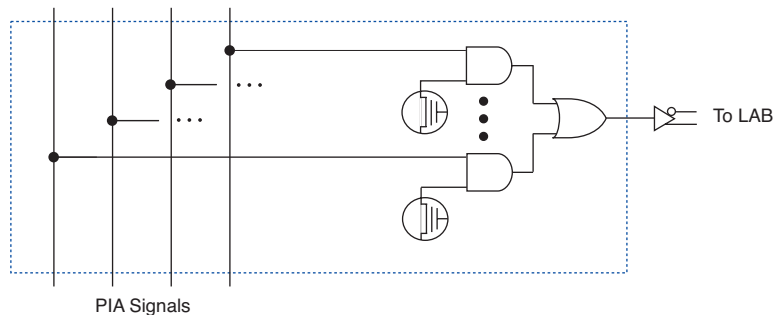
The MAX 7000 architecture includes the following elements:

- Logic array blocks
- Macrocells
- Expander product terms (shareable and parallel)
- Programmable interconnect array
- I/O control blocks

## Programmable Interconnect Array

Logic is routed between LABs via the programmable interconnect array (PIA). This global bus is a programmable path that connects any signal source to any destination on the device. All MAX 7000 dedicated inputs, I/O pins, and macrocell outputs feed the PIA, which makes the signals available throughout the entire device. Only the signals required by each LAB are actually routed from the PIA into the LAB. Figure 7 shows how the PIA signals are routed into the LAB. An EEPROM cell controls one input to a 2-input AND gate, which selects a PIA signal to drive into the LAB.

**Figure 7. PIA Routing**



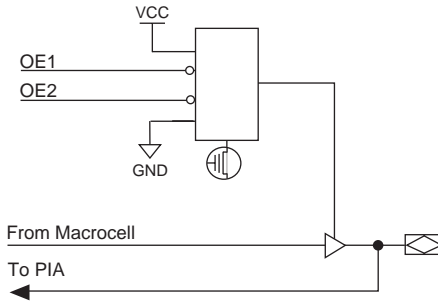
While the routing delays of channel-based routing schemes in masked or FPGAs are cumulative, variable, and path-dependent, the MAX 7000 PIA has a fixed delay. The PIA thus eliminates skew between signals and makes timing performance easy to predict.

## I/O Control Blocks

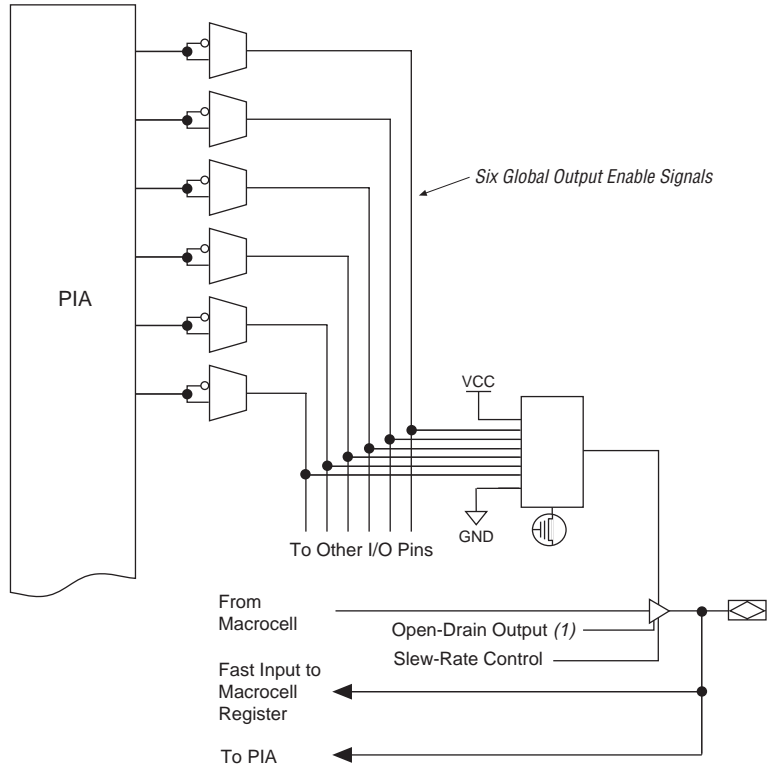
The I/O control block allows each I/O pin to be individually configured for input, output, or bidirectional operation. All I/O pins have a tri-state buffer that is individually controlled by one of the global output enable signals or directly connected to ground or  $V_{CC}$ . Figure 8 shows the I/O control block for the MAX 7000 family. The I/O control block of EPM7032, EPM7064, and EPM7096 devices has two global output enable signals that are driven by two dedicated active-low output enable pins (OE1 and OE2). The I/O control block of MAX 7000E and MAX 7000S devices has six global output enable signals that are driven by the true or complement of two output enable signals, a subset of the I/O pins, or a subset of the I/O macrocells.

**Figure 8. I/O Control Block of MAX 7000 Devices**

**EPM7032, EPM7064 & EPM7096 Devices**



**MAX 7000E & MAX 7000S Devices**



**Note:**

(1) The open-drain output option is available only in MAX 7000S devices.

By using an external 5.0-V pull-up resistor, output pins on MAX 7000S devices can be set to meet 5.0-V CMOS input voltages. When  $V_{CCIO}$  is 3.3 V, setting the open drain option will turn off the output pull-up transistor, allowing the external pull-up resistor to pull the output high enough to meet 5.0-V CMOS input voltages. When  $V_{CCIO}$  is 5.0 V, setting the output drain option is not necessary because the pull-up transistor will already turn off when the pin exceeds approximately 3.8 V, allowing the external pull-up resistor to pull the output high enough to meet 5.0-V CMOS input voltages.

### Slew-Rate Control

The output buffer for each MAX 7000E and MAX 7000S I/O pin has an adjustable output slew rate that can be configured for low-noise or high-speed performance. A faster slew rate provides high-speed transitions for high-performance systems. However, these fast transitions may introduce noise transients into the system. A slow slew rate reduces system noise, but adds a nominal delay of 4 to 5 ns. In MAX 7000E devices, when the Turbo Bit is turned off, the slew rate is set for low noise performance. For MAX 7000S devices, each I/O pin has an individual EEPROM bit that controls the slew rate, allowing designers to specify the slew rate on a pin-by-pin basis.

## Programming with External Hardware

MAX 7000 devices can be programmed on Windows-based PCs with the Altera Logic Programmer card, the Master Programming Unit (MPU), and the appropriate device adapter. The MPU performs a continuity check to ensure adequate electrical contact between the adapter and the device.



For more information, see the [Altera Programming Hardware Data Sheet](#).

The Altera development system can use text- or waveform-format test vectors created with the Text Editor or Waveform Editor to test the programmed device. For added design verification, designers can perform functional testing to compare the functional behavior of a MAX 7000 device with the results of simulation. Moreover, Data I/O, BP Microsystems, and other programming hardware manufacturers also provide programming support for Altera devices.



For more information, see the [Programming Hardware Manufacturers](#).

## IEEE Std. 1149.1 (JTAG) Boundary-Scan Support

MAX 7000 devices support JTAG BST circuitry as specified by IEEE Std. 1149.1-1990. Table 9 describes the JTAG instructions supported by the MAX 7000 family. The pin-out tables (see the Altera web site (<http://www.altera.com>) or the *Altera Digital Library* for pin-out information) show the location of the JTAG control pins for each device. If the JTAG interface is not required, the JTAG pins are available as user I/O pins.

JTAG Instruction	Devices	Description
SAMPLE/PRELOAD	EPM7128S EPM7160S EPM7192S EPM7256S	Allows a snapshot of signals at the device pins to be captured and examined during normal device operation, and permits an initial data pattern output at the device pins.
EXTEST	EPM7128S EPM7160S EPM7192S EPM7256S	Allows the external circuitry and board-level interconnections to be tested by forcing a test pattern at the output pins and capturing test results at the input pins.
BYPASS	EPM7032S EPM7064S EPM7128S EPM7160S EPM7192S EPM7256S	Places the 1-bit bypass register between the TDI and TDO pins, which allows the BST data to pass synchronously through a selected device to adjacent devices during normal device operation.
IDCODE	EPM7032S EPM7064S EPM7128S EPM7160S EPM7192S EPM7256S	Selects the IDCODE register and places it between TDI and TDO, allowing the IDCODE to be serially shifted out of TDO.
ISP Instructions	EPM7032S EPM7064S EPM7128S EPM7160S EPM7192S EPM7256S	These instructions are used when programming MAX 7000S devices via the JTAG ports with the MasterBlaster, ByteBlasterMV, BitBlaster download cable, or using a Jam File (.jam), Jam Byte-Code file (.jbc), or Serial Vector Format file (.svf) via an embedded processor or test equipment.

## Design Security

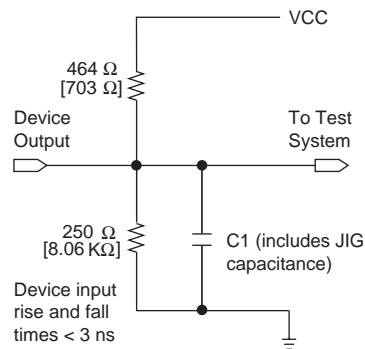
All MAX 7000 devices contain a programmable security bit that controls access to the data programmed into the device. When this bit is programmed, a proprietary design implemented in the device cannot be copied or retrieved. This feature provides a high level of design security because programmed data within EEPROM cells is invisible. The security bit that controls this function, as well as all other programmed data, is reset only when the device is reprogrammed.

## Generic Testing

Each MAX 7000 device is functionally tested. Complete testing of each programmable EEPROM bit and all internal logic elements ensures 100% programming yield. AC test measurements are taken under conditions equivalent to those shown in [Figure 10](#). Test patterns can be used and then erased during early stages of the production flow.

**Figure 10. MAX 7000 AC Test Conditions**

*Power supply transients can affect AC measurements. Simultaneous transitions of multiple outputs should be avoided for accurate measurement. Threshold tests must not be performed under AC conditions. Large-amplitude, fast ground-current transients normally occur as the device outputs discharge the load capacitances. When these transients flow through the parasitic inductance between the device ground pin and the test system ground, significant reductions in observable noise immunity can result. Numbers in brackets are for 2.5-V devices and outputs. Numbers without brackets are for 3.3-V devices and outputs.*



## QFP Carrier & Development Socket

MAX 7000 and MAX 7000E devices in QFP packages with 100 or more pins are shipped in special plastic carriers to protect the QFP leads. The carrier is used with a prototype development socket and special programming hardware available from Altera. This carrier technology makes it possible to program, test, erase, and reprogram a device without exposing the leads to mechanical stress.



For detailed information and carrier dimensions, refer to the [QFP Carrier & Development Socket Data Sheet](#).

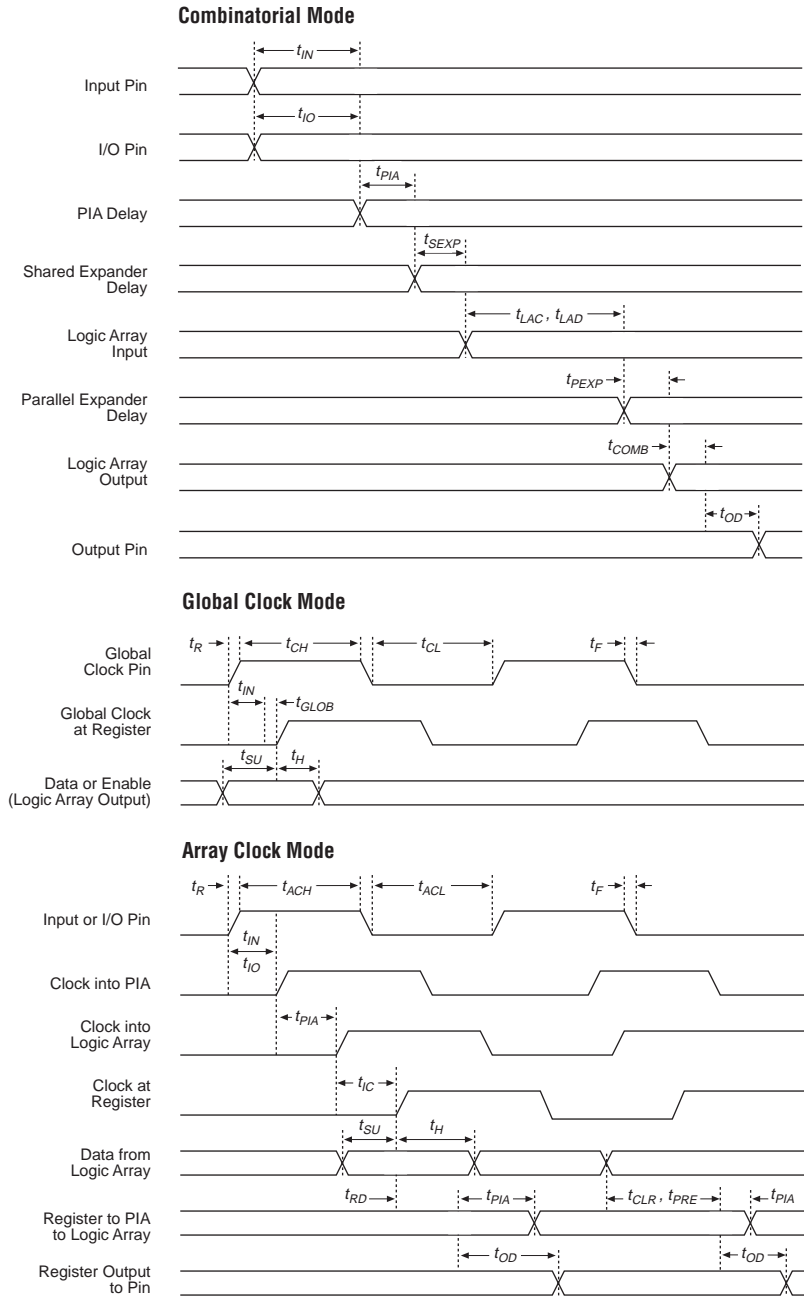


MAX 7000S devices are not shipped in carriers.



Figure 13. Switching Waveforms

$t_R$  &  $t_F < 3$  ns.  
 Inputs are driven at 3 V  
 for a logic high and 0 V  
 for a logic low. All timing  
 characteristics are  
 measured at 1.5 V.



**Table 20. MAX 7000 & MAX 7000E Internal Timing Parameters** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade -6		Speed Grade -7		Unit
			Min	Max	Min	Max	
$t_{IN}$	Input pad and buffer delay			0.4		0.5	ns
$t_{IO}$	I/O input pad and buffer delay			0.4		0.5	ns
$t_{FIN}$	Fast input delay	(2)		0.8		1.0	ns
$t_{SEXP}$	Shared expander delay			3.5		4.0	ns
$t_{PEXP}$	Parallel expander delay			0.8		0.8	ns
$t_{LAD}$	Logic array delay			2.0		3.0	ns
$t_{LAC}$	Logic control array delay			2.0		3.0	ns
$t_{IOE}$	Internal output enable delay	(2)				2.0	ns
$t_{OD1}$	Output buffer and pad delay Slow slew rate = off, $V_{CCIO} = 5.0$ V	$C1 = 35$ pF		2.0		2.0	ns
$t_{OD2}$	Output buffer and pad delay Slow slew rate = off, $V_{CCIO} = 3.3$ V	$C1 = 35$ pF (7)		2.5		2.5	ns
$t_{OD3}$	Output buffer and pad delay Slow slew rate = on, $V_{CCIO} = 5.0$ V or 3.3 V	$C1 = 35$ pF (2)		7.0		7.0	ns
$t_{ZX1}$	Output buffer enable delay Slow slew rate = off, $V_{CCIO} = 5.0$ V	$C1 = 35$ pF		4.0		4.0	ns
$t_{ZX2}$	Output buffer enable delay Slow slew rate = off, $V_{CCIO} = 3.3$ V	$C1 = 35$ pF (7)		4.5		4.5	ns
$t_{ZX3}$	Output buffer enable delay Slow slew rate = on $V_{CCIO} = 5.0$ V or 3.3 V	$C1 = 35$ pF (2)		9.0		9.0	ns
$t_{XZ}$	Output buffer disable delay	$C1 = 5$ pF		4.0		4.0	ns
$t_{SU}$	Register setup time		3.0		3.0		ns
$t_H$	Register hold time		1.5		2.0		ns
$t_{FSU}$	Register setup time of fast input	(2)	2.5		3.0		ns
$t_{FH}$	Register hold time of fast input	(2)	0.5		0.5		ns
$t_{RD}$	Register delay			0.8		1.0	ns
$t_{COMB}$	Combinatorial delay			0.8		1.0	ns
$t_{JC}$	Array clock delay			2.5		3.0	ns
$t_{EN}$	Register enable time			2.0		3.0	ns
$t_{GLOB}$	Global control delay			0.8		1.0	ns
$t_{PRE}$	Register preset time			2.0		2.0	ns
$t_{CLR}$	Register clear time			2.0		2.0	ns
$t_{PIA}$	PIA delay			0.8		1.0	ns
$t_{LPA}$	Low-power adder	(8)		10.0		10.0	ns

**Table 29. EPM7064S External Timing Parameters (Part 2 of 2)** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
$t_{ACO1}$	Array clock to output delay	C1 = 35 pF		5.4		6.7		7.5		10.0	ns
$t_{ACH}$	Array clock high time		2.5		2.5		3.0		4.0		ns
$t_{ACL}$	Array clock low time		2.5		2.5		3.0		4.0		ns
$t_{CPPW}$	Minimum pulse width for clear and preset	(2)	2.5		2.5		3.0		4.0		ns
$t_{ODH}$	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
$t_{CNT}$	Minimum global clock period			5.7		7.1		8.0		10.0	ns
$f_{CNT}$	Maximum internal global clock frequency	(4)	175.4		140.8		125.0		100.0		MHz
$t_{ACNT}$	Minimum array clock period			5.7		7.1		8.0		10.0	ns
$f_{ACNT}$	Maximum internal array clock frequency	(4)	175.4		140.8		125.0		100.0		MHz
$f_{MAX}$	Maximum clock frequency	(5)	250.0		200.0		166.7		125.0		MHz

**Table 30. EPM7064S Internal Timing Parameters (Part 1 of 2)** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
$t_{IN}$	Input pad and buffer delay			0.2		0.2		0.5		0.5	ns
$t_{IO}$	I/O input pad and buffer delay			0.2		0.2		0.5		0.5	ns
$t_{FIN}$	Fast input delay			2.2		2.6		1.0		1.0	ns
$t_{SEXP}$	Shared expander delay			3.1		3.8		4.0		5.0	ns
$t_{PEXP}$	Parallel expander delay			0.9		1.1		0.8		0.8	ns
$t_{LAD}$	Logic array delay			2.6		3.2		3.0		5.0	ns
$t_{LAC}$	Logic control array delay			2.5		3.2		3.0		5.0	ns
$t_{IOE}$	Internal output enable delay			0.7		0.8		2.0		2.0	ns
$t_{OD1}$	Output buffer and pad delay	C1 = 35 pF		0.2		0.3		2.0		1.5	ns
$t_{OD2}$	Output buffer and pad delay	C1 = 35 pF (6)		0.7		0.8		2.5		2.0	ns
$t_{OD3}$	Output buffer and pad delay	C1 = 35 pF		5.2		5.3		7.0		5.5	ns
$t_{ZX1}$	Output buffer enable delay	C1 = 35 pF		4.0		4.0		4.0		5.0	ns
$t_{ZX2}$	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		4.5		5.5	ns
$t_{ZX3}$	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		9.0	ns
$t_{XZ}$	Output buffer disable delay	C1 = 5 pF		4.0		4.0		4.0		5.0	ns
$t_{SU}$	Register setup time		0.8		1.0		3.0		2.0		ns
$t_H$	Register hold time		1.7		2.0		2.0		3.0		ns

Notes to tables:

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The  $t_{LPA}$  parameter must be added to this minimum width if the clear or reset signal incorporates the  $t_{LAD}$  parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The  $f_{MAX}$  values represent the highest frequency for pipelined data.
- (6) Operating conditions:  $V_{CCIO} = 3.3\text{ V} \pm 10\%$  for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{EN}$ ,  $t_{SEXP}$ ,  $t_{ACL}$ , and  $t_{CPPW}$  parameters for macrocells running in the low-power mode.

Tables 33 and 34 show the EPM7160S AC operating conditions.

Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
$t_{PD1}$	Input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
$t_{PD2}$	I/O input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
$t_{SU}$	Global clock setup time		3.4		4.2		7.0		11.0		ns
$t_H$	Global clock hold time		0.0		0.0		0.0		0.0		ns
$t_{FSU}$	Global clock setup time of fast input		2.5		3.0		3.0		3.0		ns
$t_{FH}$	Global clock hold time of fast input		0.0		0.0		0.5		0.0		ns
$t_{CO1}$	Global clock to output delay	C1 = 35 pF		3.9		4.8		5		8	ns
$t_{CH}$	Global clock high time		3.0		3.0		4.0		5.0		ns
$t_{CL}$	Global clock low time		3.0		3.0		4.0		5.0		ns
$t_{ASU}$	Array clock setup time		0.9		1.1		2.0		4.0		ns
$t_{AH}$	Array clock hold time		1.7		2.1		3.0		4.0		ns
$t_{ACO1}$	Array clock to output delay	C1 = 35 pF		6.4		7.9		10.0		15.0	ns
$t_{ACH}$	Array clock high time		3.0		3.0		4.0		6.0		ns
$t_{ACL}$	Array clock low time		3.0		3.0		4.0		6.0		ns
$t_{CPPW}$	Minimum pulse width for clear and preset	(2)	2.5		3.0		4.0		6.0		ns
$t_{ODH}$	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
$t_{CNT}$	Minimum global clock period			6.7		8.2		10.0		13.0	ns
$f_{CNT}$	Maximum internal global clock frequency	(4)	149.3		122.0		100.0		76.9		MHz

Table 33. EPM7160S External Timing Parameters (Part 2 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
$t_{ACNT}$	Minimum array clock period			6.7		8.2		10.0		13.0	ns
$f_{ACNT}$	Maximum internal array clock frequency	(4)	149.3		122.0		100.0		76.9		MHz
$f_{MAX}$	Maximum clock frequency	(5)	166.7		166.7		125.0		100.0		MHz

Table 34. EPM7160S Internal Timing Parameters (Part 1 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
$t_{IN}$	Input pad and buffer delay			0.2		0.3		0.5		2.0	ns
$t_{IO}$	I/O input pad and buffer delay			0.2		0.3		0.5		2.0	ns
$t_{FIN}$	Fast input delay			2.6		3.2		1.0		2.0	ns
$t_{SEXP}$	Shared expander delay			3.6		4.3		5.0		8.0	ns
$t_{PEXP}$	Parallel expander delay			1.0		1.3		0.8		1.0	ns
$t_{LAD}$	Logic array delay			2.8		3.4		5.0		6.0	ns
$t_{LAC}$	Logic control array delay			2.8		3.4		5.0		6.0	ns
$t_{IOE}$	Internal output enable delay			0.7		0.9		2.0		3.0	ns
$t_{OD1}$	Output buffer and pad delay	C1 = 35 pF		0.4		0.5		1.5		4.0	ns
$t_{OD2}$	Output buffer and pad delay	C1 = 35 pF (6)		0.9		1.0		2.0		5.0	ns
$t_{OD3}$	Output buffer and pad delay	C1 = 35 pF		5.4		5.5		5.5		8.0	ns
$t_{ZX1}$	Output buffer enable delay	C1 = 35 pF		4.0		4.0		5.0		6.0	ns
$t_{ZX2}$	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		5.5		7.0	ns
$t_{ZX3}$	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		10.0	ns
$t_{XZ}$	Output buffer disable delay	C1 = 5 pF		4.0		4.0		5.0		6.0	ns
$t_{SU}$	Register setup time		1.0		1.2		2.0		4.0		ns
$t_H$	Register hold time		1.6		2.0		3.0		4.0		ns
$t_{FSU}$	Register setup time of fast input		1.9		2.2		3.0		2.0		ns
$t_{FH}$	Register hold time of fast input		0.6		0.8		0.5		1.0		ns
$t_{RD}$	Register delay			1.3		1.6		2.0		1.0	ns
$t_{COMB}$	Combinatorial delay			1.0		1.3		2.0		1.0	ns
$t_{IC}$	Array clock delay			2.9		3.5		5.0		6.0	ns
$t_{EN}$	Register enable time			2.8		3.4		5.0		6.0	ns
$t_{GLOB}$	Global control delay			2.0		2.4		1.0		1.0	ns
$t_{PRE}$	Register preset time			2.4		3.0		3.0		4.0	ns

Tables 37 and 38 show the EPM7256S AC operating conditions.

**Table 37. EPM7256S External Timing Parameters** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-15		
			Min	Max	Min	Max	Min	Max	
$t_{PD1}$	Input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns
$t_{PD2}$	I/O input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns
$t_{SU}$	Global clock setup time		3.9		7.0		11.0		ns
$t_H$	Global clock hold time		0.0		0.0		0.0		ns
$t_{FSU}$	Global clock setup time of fast input		3.0		3.0		3.0		ns
$t_{FH}$	Global clock hold time of fast input		0.0		0.5		0.0		ns
$t_{CO1}$	Global clock to output delay	C1 = 35 pF		4.7		5.0		8.0	ns
$t_{CH}$	Global clock high time		3.0		4.0		5.0		ns
$t_{CL}$	Global clock low time		3.0		4.0		5.0		ns
$t_{ASU}$	Array clock setup time		0.8		2.0		4.0		ns
$t_{AH}$	Array clock hold time		1.9		3.0		4.0		ns
$t_{ACO1}$	Array clock to output delay	C1 = 35 pF		7.8		10.0		15.0	ns
$t_{ACH}$	Array clock high time		3.0		4.0		6.0		ns
$t_{ACL}$	Array clock low time		3.0		4.0		6.0		ns
$t_{CPW}$	Minimum pulse width for clear and preset	(2)	3.0		4.0		6.0		ns
$t_{ODH}$	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		ns
$t_{CNT}$	Minimum global clock period			7.8		10.0		13.0	ns
$f_{CNT}$	Maximum internal global clock frequency	(4)	128.2		100.0		76.9		MHz
$t_{ACNT}$	Minimum array clock period			7.8		10.0		13.0	ns
$f_{ACNT}$	Maximum internal array clock frequency	(4)	128.2		100.0		76.9		MHz
$f_{MAX}$	Maximum clock frequency	(5)	166.7		125.0		100.0		MHz

**Notes to tables:**

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The  $t_{LPA}$  parameter must be added to this minimum width if the clear or reset signal incorporates the  $t_{LAD}$  parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The  $f_{MAX}$  values represent the highest frequency for pipelined data.
- (6) Operating conditions:  $V_{CCIO} = 3.3\text{ V} \pm 10\%$  for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{EN}$ ,  $t_{SEXP}$ ,  $t_{ACL}$ , and  $t_{CPPW}$  parameters for macrocells running in the low-power mode.

## Power Consumption

Supply power (P) versus frequency ( $f_{MAX}$  in MHz) for MAX 7000 devices is calculated with the following equation:

$$P = P_{INT} + P_{IO} = I_{CCINT} \times V_{CC} + P_{IO}$$

The  $P_{IO}$  value, which depends on the device output load characteristics and switching frequency, can be calculated using the guidelines given in [Application Note 74 \(Evaluating Power for Altera Devices\)](#).

The  $I_{CCINT}$  value, which depends on the switching frequency and the application logic, is calculated with the following equation:

$$I_{CCINT} = A \times MC_{TON} + B \times (MC_{DEV} - MC_{TON}) + C \times MC_{USED} \times f_{MAX} \times \text{tog}_{LC}$$

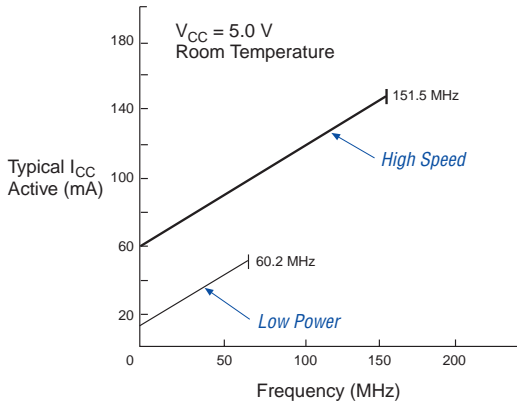
The parameters in this equation are shown below:

$MC_{TON}$	=	Number of macrocells with the Turbo Bit option turned on, as reported in the MAX+PLUS II Report File (.rpt)
$MC_{DEV}$	=	Number of macrocells in the device
$MC_{USED}$	=	Total number of macrocells in the design, as reported in the MAX+PLUS II Report File (.rpt)
$f_{MAX}$	=	Highest clock frequency to the device
$\text{tog}_{LC}$	=	Average ratio of logic cells toggling at each clock (typically 0.125)
A, B, C	=	Constants, shown in <a href="#">Table 39</a>

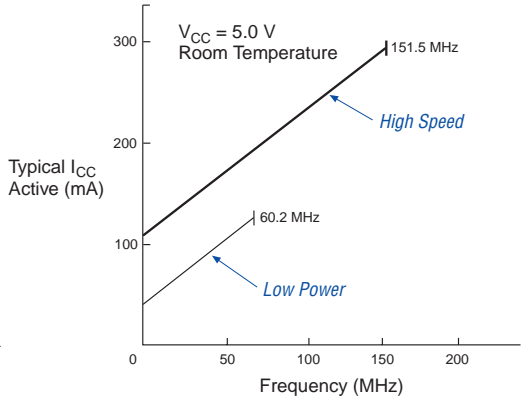
Figure 14 shows typical supply current versus frequency for MAX 7000 devices.

Figure 14.  $I_{CC}$  vs. Frequency for MAX 7000 Devices (Part 1 of 2)

EPM7032



EPM7064



EPM7096

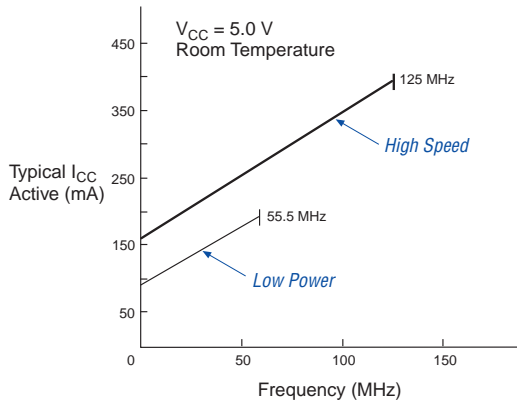
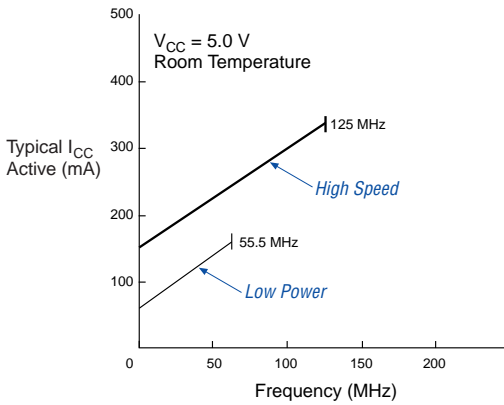


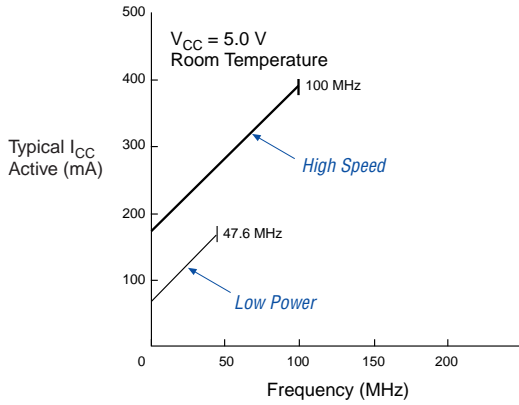


Figure 14.  $I_{CC}$  vs. Frequency for MAX 7000 Devices (Part 2 of 2)

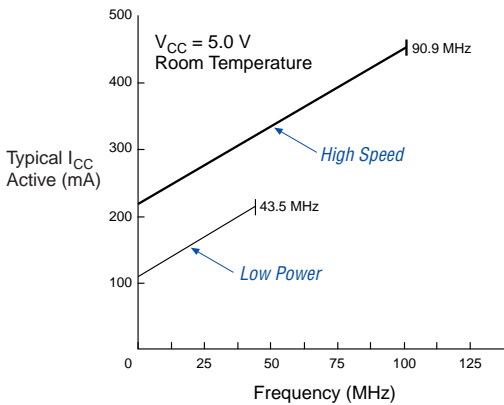
EPM7128E



EPM7160E



EPM7192E



EPM7256E

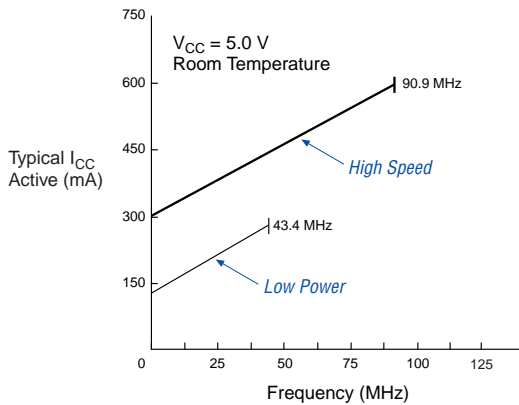
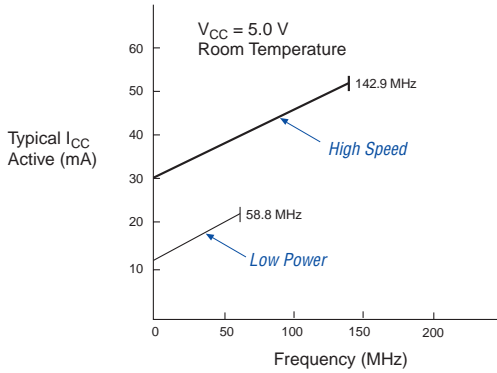


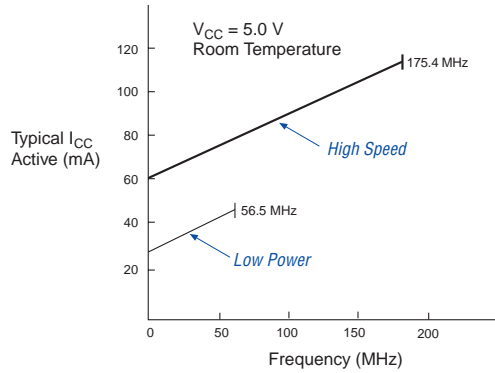
Figure 15 shows typical supply current versus frequency for MAX 7000S devices.

Figure 15.  $I_{CC}$  vs. Frequency for MAX 7000S Devices (Part 1 of 2)

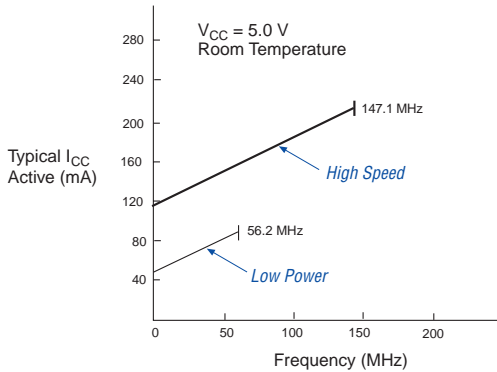
EPM7032S



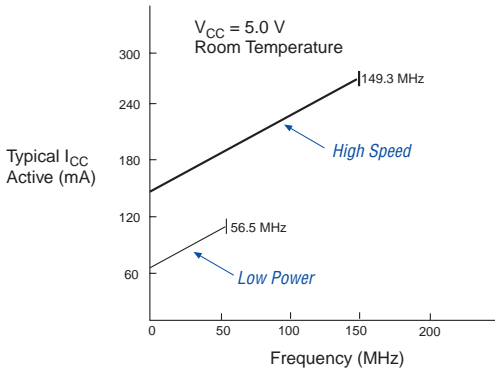
EPM7064S



EPM7128S

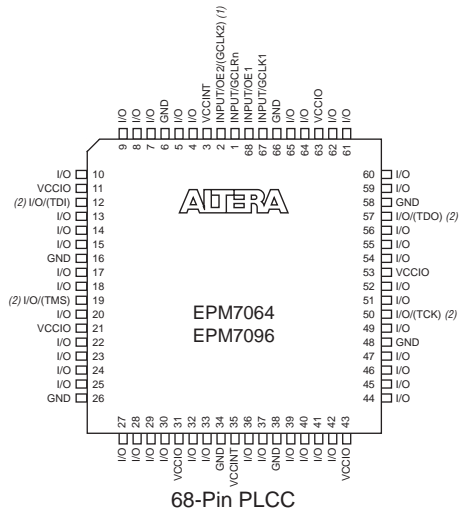


EPM7160S



**Figure 17. 68-Pin Package Pin-Out Diagram**

Package outlines not drawn to scale.

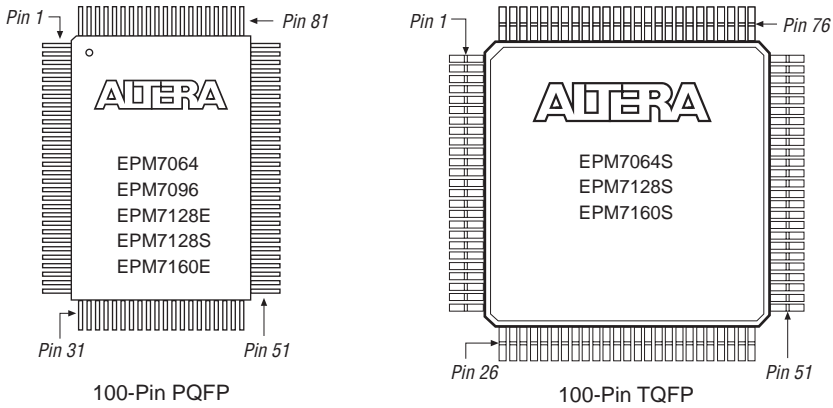


**Notes:**

- (1) The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
- (2) JTAG ports are available in MAX 7000S devices only.

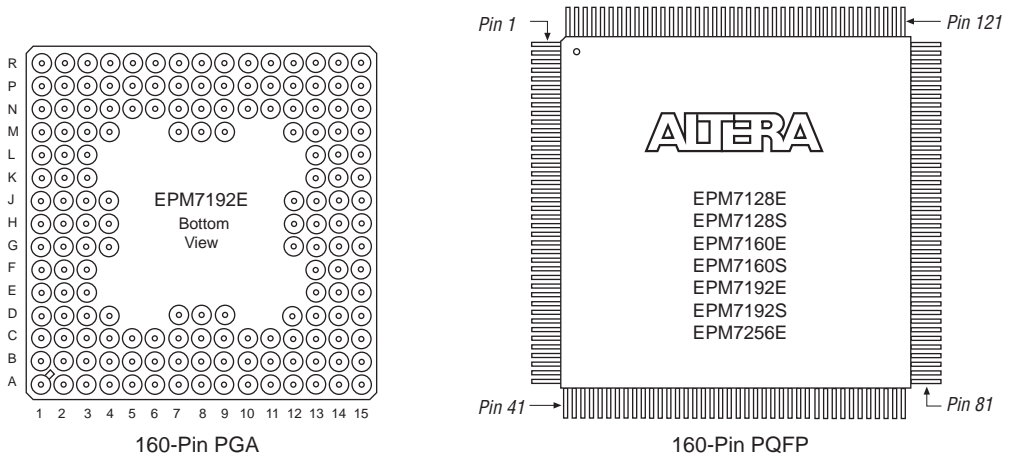
**Figure 19. 100-Pin Package Pin-Out Diagram**

Package outline not drawn to scale.



**Figure 20. 160-Pin Package Pin-Out Diagram**

Package outline not drawn to scale.





101 Innovation Drive  
San Jose, CA 95134  
(408) 544-7000  
[www.altera.com](http://www.altera.com)  
[Applications Hotline:  
\(800\) 800-EPLD](tel:800800EPLD)  
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literature@altera.com](mailto:literature@altera.com)

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